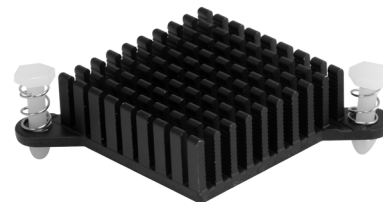




MODEL: HSB25-282810 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- small footprint
- top mount
- aluminum alloy



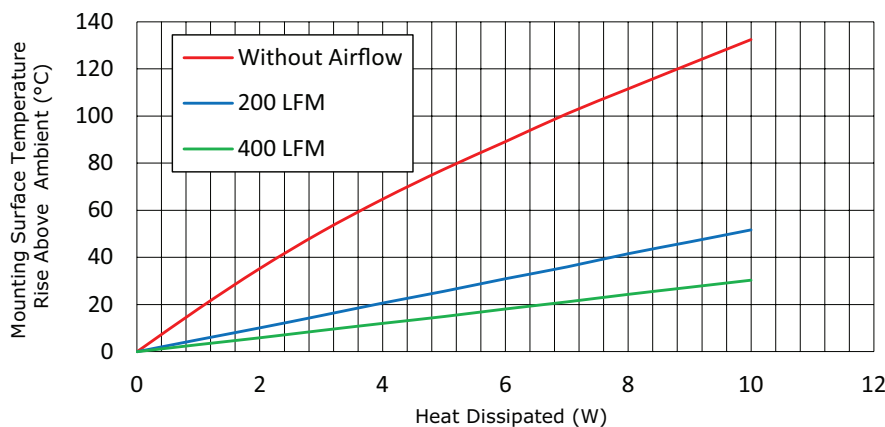
MODEL

	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	
HSB25-282810	15.41	18.2	5.1	3.0	4.87

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power [W]	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	18.2	5.1	3.0
2	35.3	10.1	5.9
3	50.8	15.3	9.0
4	64.7	20.6	12.0
5	77.4	25.6	14.9
6	89.1	30.9	18.1
7	100.9	35.9	21.1
8	111.5	41.5	24.3
9	122.0	46.5	27.3
10	132.4	51.6	30.3



T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
PUSH PIN	PA66
SPRING	spring steel, nickel plated
WEIGHT	13.9 g

